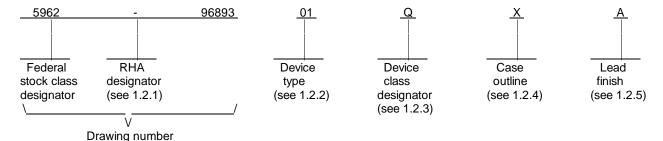
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PMIC N/A				Da	n Wonr	nell				DEFENSE SUPPLY CENTER COLUMBUS COLUMBUS, OHIO 43216										
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## 1. SCOPE

- 1.1 <u>Scope</u>. This drawing documents two product assurance class levels consisting of high reliability (device classes Q and M) and space application (device class V). A choice of case outlines and lead finishes are available and are reflected in the Part or Identifying Number (PIN). When available, a choice of Radiation Hardness Assurance (RHA) levels are reflected in the PIN.
  - 1.2 PIN. The PIN is as shown in the following example:



- 1.2.1 RHA designator. Device classes Q and V RHA marked devices meet the MIL-PRF-38535 specified RHA levels and are marked with the appropriate RHA designator. Device class M RHA marked devices meet the MIL-PRF-38535, appendix A specified RHA levels and are marked with the appropriate RHA designator. A dash (-) indicates a non-RHA device.
  - 1.2.2 <u>Device type(s)</u>. The device type(s) identify the circuit function as follows:

Skew limit											
Device type	Generic number	<u>Driver</u>	<u>Receiver</u>	Circuit function							
01	55976A1	8	9	9 Channel Differential Transceiver							
02	55976A2	4	5	9 Channel Differential Transceiver							

1.2.3 Device class designator. The device class designator is a single letter identifying the product assurance level as follows:

Device class

Device requirements documentation

M

Vendor self-certification to the requirements for MIL-STD-883 compliant, non-JAN class level B microcircuits in accordance with MIL-PRF-38535, appendix A

Q or V

Certification and qualification to MIL-PRF-38535

1.2.4 Case outline(s). The case outline(s) are as designated in MIL-STD-1835 and as follows:

Outline letter	Descriptive designator	<u>Terminals</u>	Package style
X	GDFP1-F56	56	Dual Flat Pack

1.2.5 <u>Lead finish</u>. The lead finish is as specified in MIL-PRF-38535 for device classes Q and V or MIL-PRF-38535, appendix A for device class M.

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# 1.3 Absolute maximum ratings. 1/, 2/ B side and GND, Class 3, B: ..... 400 V All terminals, Class 3, A: ..... 4 kV All terminals, Class 3, B: 400 V Storage temperature range (T<sub>STG</sub>) .... -65° C to +150° C Lead temperature, soldering 1.6 mm (1/16 inch) from case for 10 seconds ... +260°C Junction-to-ambient thermal resistance, $(\Theta_{JA})$ . 95.4°C/W Junction-to-case thermal resistance, $(\Theta_{JC})$ . 5.67°C/W Thermal-shutdown junction temperature, $(T_{JS})$ . 165°C Maximum power dissipation at $T_A$ = 125°C (in still air) $(P_D)$ . 260°mW 1.4 Recommended operating conditions. (Receiver) -8 mA Low level output current (I<sub>OL</sub>) (Driver) +60 mA 1/ Stresses above the absolute maximum rating may cause permanent damage to the device. Extended operation at the maximum levels may degrade performance and affect reliability. Unless otherwise noted, all voltages are referenced to GND. 3/ This absolute maximum rating is tested in accordance with MIL-STD-883C, Method 3015.7.

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#### 2. APPLICABLE DOCUMENTS

2.1 <u>Government specification, standards, and handbooks</u>. The following specification, standards, and handbooks form a part of this drawing to the extent specified herein. Unless otherwise specified, the issues of these documents are those listed in the issue of the Department of Defense Index of Specifications and Standards (DoDISS) and supplement thereto, cited in the solicitation.

#### **SPECIFICATION**

**MILITARY** 

MIL-PRF-38535 - Integrated Circuits, Manufacturing, General Specification for.

## **STANDARDS**

**MILITARY** 

MIL-STD-883 - Test Methods and Procedures for Microelectronics.

MIL-STD-973 - Configuration Management.

MIL-STD-1835 - Microcircuit Case Outlines.

## **HANDBOOKS**

**MILITARY** 

MIL-HDBK-103 - List of Standard Microcircuit Drawings (SMD's).

MIL-HDBK-780 - Standard Microcircuit Drawings.

(Unless otherwise indicated, copies of the specification, standards, and handbooks are available from the Standardization Document Order Desk, 700 Robbins Avenue, Building 4D, Philadelphia, PA 19111-5094.)

2.2 <u>Order of precedence</u>. In the event of a conflict between the text of this drawing and the references cited herein, the text of this drawing takes precedence. Nothing in this document, however, supersedes applicable laws and regulations unless a specific exemption has been obtained.

## 3. REQUIREMENTS

- 3.1 <u>Item requirements</u>. The individual item requirements for device classes Q and V shall be in accordance with MIL-PRF-38535 and as specified herein or as modified in the device manufacturer's Quality Management (QM) plan. The modification in the QM plan shall not affect the form, fit, or function as described herein. The individual item requirements for device class M shall be in accordance with MIL-PRF-38535, appendix A for non-JAN class level B devices and as specified herein.
- 3.2 <u>Design, construction, and physical dimensions</u>. The design, construction, and physical dimensions shall be as specified in MIL-PRF-38535 and herein for device classes Q and V or MIL-PRF-38535, appendix A and herein for device class M.
  - 3.2.1 Case outline(s). The case outline(s) shall be in accordance with 1.2.4 herein.
  - 3.2.2 <u>Terminal connections</u>. The terminal connections shall be as specified on figure 1.
  - 3.2.3 <u>Truth table(s)</u>. The truth table(s) shall be as specified on figure 2.

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- 3.3 <u>Electrical performance characteristics and postirradiation parameter limits</u>. Unless otherwise specified herein, the electrical performance characteristics and postirradiation parameter limits are as specified in table I and shall apply over the full ambient operating temperature range.
- 3.4 <u>Electrical test requirements</u>. The electrical test requirements shall be the subgroups specified in table II. The electrical tests for each subgroup are defined in table I.
- 3.5 <u>Marking</u>. The part shall be marked with the PIN listed in 1.2 herein. In addition, the manufacturer's PIN may also be marked as listed in MIL-HDBK-103. For packages where marking of the entire SMD PIN number is not feasible due to space limitations, the manufacturer has the option of not marking the "5962-" on the device. For RHA product using this option, the RHA designator shall still be marked. Marking for device classes Q and V shall be in accordance with MIL-PRF-38535. Marking for device class M shall be in accordance with MIL-PRF-38535, appendix A.
- 3.5.1 <u>Certification/compliance mark</u>. The certification mark for device classes Q and V shall be a "QML" or "Q" as required in MIL-PRF-38535. The compliance mark for device class M shall be a "C" as required in MIL-PRF-38535, appendix A.
- 3.6 <u>Certificate of compliance</u>. For device classes Q and V, a certificate of compliance shall be required from a QML-38535 listed manufacturer in order to supply to the requirements of this drawing (see 6.6.1 herein). For device class M, a certificate of compliance shall be required from a manufacturer in order to be listed as an approved source of supply in MIL-HDBK-103 (see 6.6.2 herein). The certificate of compliance submitted to DSCC-VA prior to listing as an approved source of supply for this drawing shall affirm that the manufacturer's product meets, for device classes Q and V, the requirements of MIL-PRF-38535 and herein or for device class M, the requirements of MIL-PRF-38535, appendix A and herein.
- 3.7 <u>Certificate of conformance</u>. A certificate of conformance as required for device classes Q and V in MIL-PRF-38535 or for device class M in MIL-PRF-38535, appendix A shall be provided with each lot of microcircuits delivered to this drawing.
- 3.8 <u>Notification of change for device class M.</u> For device class M, notification to DSCC-VA of change of product (see 6.2 herein) involving devices acquired to this drawing is required for any change as defined in MIL-STD-973.
- 3.9 <u>Verification and review for device class M</u>. For device class M, DSCC, DSCC's agent, and the acquiring activity retain the option to review the manufacturer's facility and applicable required documentation. Offshore documentation shall be made available onshore at the option of the reviewer.
- 3.10 <u>Microcircuit group assignment for device class M.</u> Device class M devices covered by this drawing shall be in microcircuit group number 77 (see MIL-PRF-38535, appendix A).

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TABLE I. Electrical performance characteristics.										
Test and MIL-STD-883	Symbol Test conditions $\underline{2}/$ -55° C $\leq$ T <sub>A</sub> $\leq$ +125° C			V <sub>CC</sub>	Device type	Group A subgroups	Limi	Unit		
test method 1/		+4.75 V ≤ V <sub>CC</sub> unless otherwi	> ≤ +5.25 V				Min	Max		
Driver differential high-	V <sub>ODH</sub>	OH S1 to A, V <sub>T</sub> = 5 V 4.75 V	1	1.0		V				
level output voltage		see figure 3		to 5.25 V	All	2, 3	0.7			
		S1 to B,				1	0.8			
		see figure 3				2, 3	0.7			
Driver differential low-	V <sub>ODL</sub>	$V_{ODL}$	S1 to B,	V <sub>T</sub> = 5 V	4.75 V		1		-1.0	V
level output voltage		see figure 3		to 5.25 V	All	2, 3		-0.7		
		S1 to A,				1		-0.8		
		see figure 3				2, 3		-0.7		
High level output voltage	V <sub>OH</sub>	A side, V <sub>ID</sub> = 200 mV see figure 4	I <sub>OH</sub> = -8 mA	4.75 V to 5.25 V	All	1, 2, 3	4.0		V	
Low level output voltage	V <sub>OL</sub>	A side, V <sub>ID</sub> = -200 mV see figure 4	I <sub>OL</sub> = 8 mA	4.75 V to 5.25 V	All	1, 2, 3		0.8	V	

 $I_{OH}$  = -8 mA, see figure 4

 $I_{OL}$  = 8 mA, see figure 4

 $V_{IH}$  = 12 V, Other input at 0 V

 $V_{IH}$  = -7 V, Other input at 0 V

 $V_{IH} = 2.0 V$ 

 $V_{IH} = 0.8 V$ 

 $T_A = 25^{\circ}C$ 

A, BSR, CRE,

CDE0, CDE1

A, BSR, CRE,

and DE/RE

CDE1, CDE1

and CDE2

and DE/RE

and CDE2

ΑII

ΑII

ΑII

ΑII

ΑII

ΑII

1, 2, 3

1, 2, 3

1

1, 2, 3

1, 2, 3

1, 2, 3

24.0

0.2

-0.2

1.0

1.0

-0.8

-0.8

-100

+100

-100

+100

V

٧

mV

mΑ

μΑ

μΑ

4.75 V

to 5.25 V

4.75 V

to 5.25 V

5.0 V

5.0 V

0.0 V

5.0 V

0.0 V

4.75 V

to 5.25 V

4.75 V

to

5.25 V

See footnotes at end of table.

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Receiver positive

differential input

Receiver negative

differential input

Receiver input

Bus input current

High-level input

Low-level input

current

current

threshold voltage

hysteresis ( $V_{IT+}$  -  $V_{IT-}$ )

threshold voltage

 $V_{IT+}$ 

 $V_{IT-}$ 

 $V_{\mathrm{hys}}$ 

 $I_{H}$ 

 $I_{IL}$ 

TABLE I. <u>Electrical performance characteristics</u> - conti	nued.
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Test and MIL-STD-883	Symbol	Test conditions 2/ -55° C ≤ T <sub>Δ</sub> ≤ +125° C	V <sub>CC</sub>	Device type	Group A subgroups	Lim	its <u>3</u> /	Unit
test method 1/		$-55^{\circ}$ C $\leq$ T <sub>A</sub> $\leq$ +12 $\overline{5}^{\circ}$ C +4.75 V $\leq$ V <sub>CC</sub> $\leq$ +5.25 V unless otherwise specified				Min	Max	
Short circuit output current	los	nB+ or nB-	4.75 V to 5.25 V	All	1, 2, 3		±260	mA
Supply current	I <sub>CC</sub>	Disabled	4.75 V		1, 2, 3		10.0	mA
		All drivers enabled, no load	to 5.25 V	All			60.0	
		All receivers enabled, no load					45.0	
Driver Switching Chara	cteristics							
Functional test 3014	<u>4</u> /	$V_{IH}$ = 2.0 V, $V_{IL}$ = 0.8 V Verify output $V_{O}$ see 4.4.1b	4.75 V to 5.25 V	All	7, 8	L	Н	
Propagation delay		t <sub>pd</sub> see figure 3	5.0 V		9	3.0	11.0	ns
time, t <sub>PHL</sub> or t <sub>PLH</sub>				01	10, 11		15.0	
					9	5.0	9.0	]
				02	10, 11		13.5	
Skew limit, maximum	t <sub>sk(lim)</sub>		4.75 V	01	9, 10, 11		8.0	ns
t <sub>pd</sub> - minimum t <sub>pd</sub>	<u>5</u> /		to 5.25 V	02			4.0	
Pulse skew,  t <sub>PHL</sub> -	t <sub>sk(p)</sub>		4.75 V to 5.25 V	All	9, 10, 11		4.0	ns
Enable time, control	t <sub>en</sub>		4.75 V		9		50.0	ns
inputs to active output			to 5.25 V	All	10, 11		60.0	
Disable time, control	t <sub>dis</sub>		4.75 V	All	9		100	ns
inputs to high impedance output			to 5.25 V		10, 11		140	

See footnotes at end of table.

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Test and MIL-STD-883	Symbol	-55° C < T₄ < +125° C		Device type	Group A subgroups	Limi	ts <u>3</u> /	Unit
test method 1/		$+4.5 \text{ V} \le \text{V}_{CC} \le +5.5 \text{ V}$ unless otherwise specified	≤ +5.5 V e specified		- 0429.04P0	Min	Max	
Propagation delay time, high-level to	t <sub>PHZ</sub>	see figure 5	4.75 V to	All	9		100	ns
high impedance output			5.25 V		10, 11		120	
Propagation delay time, low-level to	t <sub>PLZ</sub>	see figure 5	4.75 V to All		9		100	ns
high impedance output			5.25 V		10, 11		120	
Propagation delay time, high	<sup>t</sup> PZH	see figure 5	4.75 V to		9		50.0	ns
impedance to high- level output			5.25 V	5.25 V All			60.0	
Propagation delay time, high	t <sub>PZL</sub>		4.75 V to		9		50.0	
impedance to low-level output	pedance to		5.25 V		10, 11		60.0	
Receiver switching cha	aracteristics	S						
Functional test 3014	<u>4</u> /	V <sub>IH</sub> = 2.0 V, V <sub>IL</sub> = 0.8 V Verify output V <sub>O</sub> see 4.4.1b	4.75 V to 5.25 V	All	7, 8	L	Н	
Propagation delay time, t <sub>PHL</sub> or t <sub>PLH</sub>	t <sub>pd</sub>	see figure 4	5.0 V	01	9	7.5	16.5	ns
WING, THE OF THE				01	10, 11		19.0	
				00	9	8.6	13.6	
				02	10, 11		16.0	
Skew limit, maximum t <sub>pd</sub> - minimum t <sub>pd</sub>	t <sub>sk(lim)</sub>		4.75 V to	01	9, 10, 11		9.0	ns
rpd minimum rpd	<u>5</u> /		5.25 V	02			5.0	
Pulse skew, $ t_{PHL}$ - $t_{PLH} $	t <sub>sk(p)</sub>		4.75 V to 5.25 V	All	9, 10, 11		4.0	ns
Enable time, control	t <sub>en</sub>	4.75 V	A.II	9		50.0	ns	
inputs to active output		to 5.25 V	All	10, 11		70.0		
Disable time, control inputs to high-	t <sub>dis</sub>		4.75 V to	All	9		60.0	ns
impedance output			5.25 V		10, 11		80.0	

See footnotes at end of table.

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TABLE I. <u>Electrical performance characteristics</u> - continued.

Test and MIL-STD-883	Symbol	Symbol Test conditions $\underline{2}/$ -55° C $\leq$ T <sub>A</sub> $\leq$ +125° C		Device		Limits 3/		Unit
test method 1/		+4.5 V ≤ V <sub>CC</sub> ≤ +5.5 V unless otherwise specified	≥ +5.5 V		Subgroups	Min	Max	
Propagation delay	t <sub>PHZ</sub>	see figure 6	4.75 V		9		60.0	ns
time, high-level to high impedance output			to 5.25 V	A 11	10, 11		80.0	
Propagation delay	t <sub>PLZ</sub>		4.75 V to 5.25 V		9		50.0	
time, low-level to high impedance output					10, 11		70.0	
Propagation delay	t <sub>PZH</sub>	see figure 6	4.75 V		9		50.0	ns
time, high impedance to high-level output			to 5.25 V	A 11	10, 11		70.0	
Propagation delay	t <sub>PZL</sub>		4.75 V	All	9		50.0	
time, high impedance to low-level output			to 5.25 V		10, 11		70.0	

- 1/ For tests not listed in the referenced MIL-STD-883, utilize the general test procedure of 883 under the conditions listed herein.
- Each input/output, as applicable, shall be tested at the specified temperature, for the specified limits, to the tests in table I herein. Output terminals not designated shall be high level logic, low level logic, or open, except for all I<sub>CC</sub> tests, where the output terminals shall be open. When performing these tests, the current meter shall be placed in the circuit such that all current flows through the meter.
- 3/ For negative and positive voltage and current values, the sign designates the potential difference in reference to GND and the direction of current flow, respectively; and the absolute value of the magnitude, not the sign, is relative to the minimum and maximum limits, as applicable, listed herein.
- 4/ Tests shall be performed in sequence, attributes data only. Functional tests shall include the truth table and other logic patterns used for fault detection. The test vectors used to verify the truth table shall, at a minimum, test all functions of each input and output. All possible input to output logic patterns per function shall be guaranteed, if not tested, to the truth table in figure 2 herein. Functional tests shall be performed in sequence as approved by the qualifying activity on qualified devices. After incorporating allowable tolerances per MIL-STD-883, V<sub>IL</sub> = 0.4 V and V<sub>IH</sub> = 2.4 V. For outputs, L ≤ 0.8 V, H ≥ 2.0 V.
- 5/ This parameter is applicable at one V<sub>CC</sub> and operating temperature within the recommended operating conditions and to any two devices.

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FIGURE 1. <u>Terminal connections</u>.

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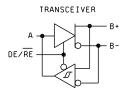
	Terminal Functions							
Terminal	Logic level	I/O	Termination	Description				
mA (m = 1 to 9)	TTL	I/O	Pullup	1A to 9A carry data to and from the cmmunication controller.				
mB- (m = 1 to 9)	RS-485	I/O	Pulldown	1B- to 9B- are the inverted data signals of the balanced pair to/from the bus.				
mB+ (m = 1 to 9)	RS-485	I/O	Pullup	1B+ to 9B+ are the noninverted data signals of the balanced pair to/from the bus.				
BSR	TTL	Input	Pullup	BSR is the bit significant response. BSR disables receivers 1 through 8 and enables wired-OR drivers when BSR and DE/RE and CDE1 or CDE2 are high. Channel 9 is placed in a high-impedance state with BSR high.				
CDE0	TTL	Input	Pulldown	CDE0 is the common driver enable 0. Its input signal enables all drivers when CDE0 and 1DE/RE - 9DE/RE are high.				
CDE1	TTL	Input	Pulldown	CDE1 is the common driver enable 1. Its input signal enables drivers 1 to 4 when CDE1 is high and BSR is low.				
CDE2	TTL	Input	Pulldown	CDE2 is the common driver enable 2. When CDE2 is high and BSR is low, drivers 5 to 8 are enabled.				
CRE	TTL	Input	Pullup	CRE is the common receiver enable. When high, CRE disables receiver channels 5 to 9.				
mDE/RE (m = 1 to 9)	TTL	Input	Pullup	1DE/RE - 9DE/RE are direction controls that transmit data to the bus when it and CDE0 are high. Data is received from the bus when 1DE/RE - 9DE/RE and CRE and BSR are low and CDE1 and CDE2 are low.				

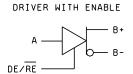
FIGURE 1. <u>Terminal connections</u> - continued.

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INPUTS		OUTPUT
B+ <u>1</u> /	B- <u>1</u> /	А
L	Н	L
Н	L	Н

INPUT	OUTPUTS		
Α	B+	B-	
L	L	Н	
Н	Н	L	





INPUTS			0	UTPUT	ſS	
DE/RE	Α	B+ <u>1</u> /	B- <u>1</u> /	Α	B+	B-
L	-	L H	H L	L H	-	١.،
H H	L H	-	-	-	L H	H L

INPL	JTS	OUT	PUTS
DE/RE	А	B+	B-
L L H	L H L H	Z Z L H	Z Z H L



TWO-ENABLE	INPUT	DRIVER
Α —	1	— В+
" [_	1	)— В-
DE/RE —		

INPUT A	OUTPUTS		
	B+	B-	
L H	Z H	Z L	

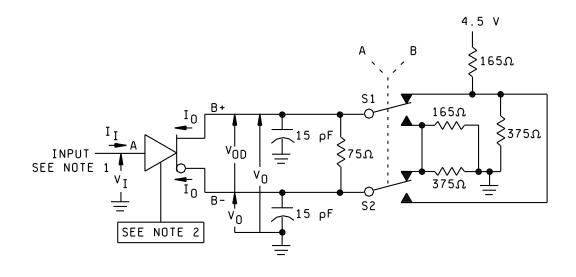
INPUTS		OUTPUTS	
DE/RE	Α	B+	B-
L L H	L H L	Z H L H	Z L H L

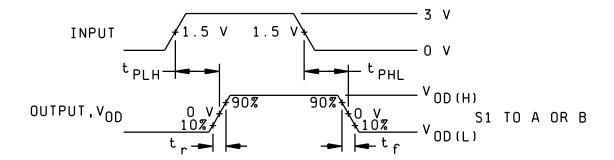
NOTES: H = high level, L = low level, Z = high impedance (off).

1/ "H" in this column represents a voltage of 200 mV or higher than the other bus input. "L" represents a voltage of 200 mV or lower than the other bus input. Any voltage less than 200 mV results in an indeterminate receiver output.

FIGURE 2. Truth table.

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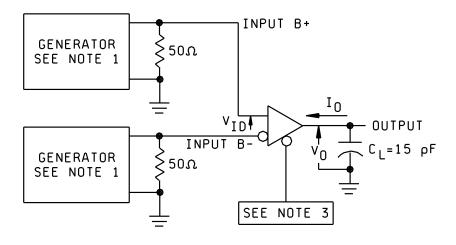


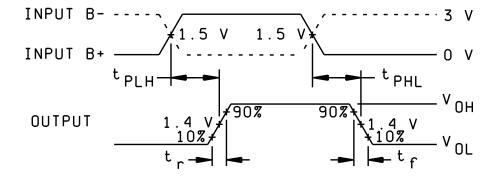


- All input pulses are supplied by a generator having the following characteristics: t<sub>r</sub> ≤ 6 ns, t<sub>f</sub> ≤ 6 ns, PRR ≤ 1 Mhz, duty cycle = 50%, Z<sub>O</sub> = 50Ω.
   CDE0 and DE/RE are at 2 V, BSR is at 0.8 V.
- 3. All resistances are ±5%, unless otherwise indicated.
- 4. All capacitances are ±10%, unless otherwise indicated.
- 5. All indicated voltages are ±10 mV.

FIGURE 3. Driver delay and transition test circuit and timing waveforms.

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- All input pulses are supplied by a generator having the following characteristics: t<sub>r</sub> ≤ 6 ns, t<sub>f</sub> ≤ 6 ns, PRR ≤ 1 Mhz, duty cycle = 50%, Z<sub>O</sub> = 50Ω.
   All indicated voltages are ±10 mV.
   CDE1, CDE2, BSR, CRE, and DE/RE at 0.8 V.

- 4. All resistances are ±5%, unless otherwise indicated.
- 5. All capacitances are ±10%, unless otherwise indicated.

FIGURE 4. Receiver delay and transition test circuit and timing waveforms.

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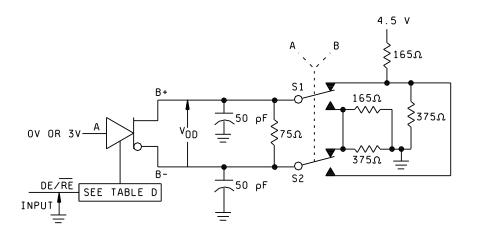
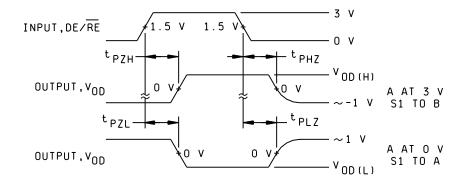


TABLE D. Enabling for driver enable and disable time.

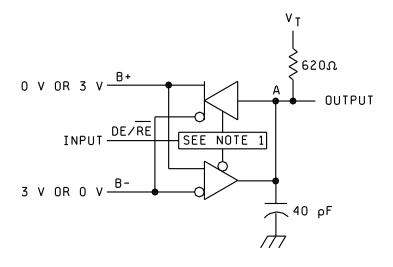
DRIVER	BSR	CDE0	CDE1	CDE2	CRE
1 - 8	Н	Н	L	L	Х
9	L	Н	Н	Н	Н

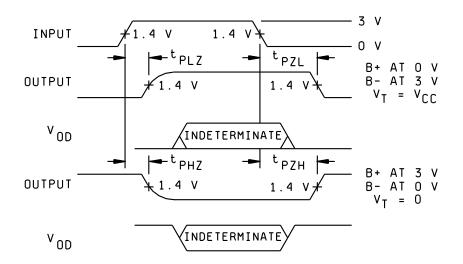


- All input pulses are supplied by a generator having the following characteristics: t<sub>r</sub> ≤ 6 ns, t<sub>f</sub> ≤ 6 ns, PRR ≤ 1 Mhz, duty cycle = 50%, Z<sub>O</sub> = 50Ω.
   All indicated voltages are ±10 mV.
- 3. All resistances are ±5%, unless otherwise indicated.
- 4. All capacitances are ±10%, unless otherwise indicated.

FIGURE 5. Driver enable and disable time test circuit and timing waveforms.

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- CDE0 is high, CDE1, CDE2, BSR, and CRE are low.
   All input pulses are supplied by a generator having the following characteristics: t<sub>r</sub> ≤ 6 ns, t<sub>f</sub> ≤ 6 ns, PRR ≤ 1 Mhz, duty cycle = 50%, Z<sub>O</sub> = 50Ω.
   All indicated voltages are ±10 mV.
   All resistances are ±5%, unless otherwise indicated.

- 5. All capacitances are ±10%, unless otherwise indicated.

FIGURE 5. Receiver enable and disable time test circuit and timing waveforms.

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#### 4. QUALITY ASSURANCE PROVISIONS

- 4.1 <u>Sampling and inspection</u>. For device classes Q and V, sampling and inspection procedures shall be in accordance with MIL-PRF-38535 or as modified in the device manufacturer's Quality Management (QM) plan. The modification in the QM plan shall not affect the form, fit, or function as described herein. For device class M, sampling and inspection procedures shall be in accordance with MIL-PRF-38535, appendix A.
- 4.2 <u>Screening</u>. For device classes Q and V, screening shall be in accordance with MIL-PRF-38535, and shall be conducted on all devices prior to qualification and technology conformance inspection. For device class M, screening shall be in accordance with method 5004 of MIL-STD-883, and shall be conducted on all devices prior to quality conformance inspection.
  - 4.2.1 Additional criteria for device class M.
    - a. Burn-in test, method 1015 of MIL-STD-883.
      - (1) Test condition A, B, C or D. The test circuit shall be maintained by the manufacturer under document revision level control and shall be made available to the preparing or acquiring activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in test method 1015.
      - (2)  $T_A = +125^{\circ} C$ , minimum.
    - b. Interim and final electrical test parameters shall be as specified in table II herein.
  - 4.2.2 Additional criteria for device classes Q and V.
    - a. The burn-in test duration, test condition and test temperature, or approved alternatives shall be as specified in the device manufacturer's QM plan in accordance with MIL-PRF-38535. The burn-in test circuit shall be maintained under document revision level control of the device manufacturer's Technology Review Board (TRB) in accordance with MIL-PRF-38535 and shall be made available to the acquiring or preparing activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in test method 1015 of MIL-STD-883.
    - b. Interim and final electrical test parameters shall be as specified in table II herein.
    - Additional screening for device class V beyond the requirements of device class Q shall be as specified in MIL-PRF-38535, appendix B.
- 4.3 <u>Qualification inspection for device classes Q and V.</u> Qualification inspection for device classes Q and V shall be in accordance with MIL-PRF-38535. Inspections to be performed shall be those specified in MIL-PRF-38535 and herein for groups A, B, C, D, and E inspections (see 4.4.1 through 4.4.4).
- 4.4 <u>Conformance inspection</u>. Technology conformance inspection for classes Q and V shall be in accordance with MIL-PRF-38535 including groups A, B, C, D, and E inspections and as specified herein except where option 2 of MIL-PRF-38535 permits alternate in-line control testing. Quality conformance inspection for device class M shall be in accordance with MIL-PRF-38535, appendix A and as specified herein. Inspections to be performed for device class M shall be those specified in method 5005 of MIL-STD-883 and herein for groups A, B, C, D, and E inspections (see 4.4.1 through 4.4.4).
  - 4.4.1 Group A inspection.
    - a. Tests shall be as specified in table II herein.
    - b. For device class Q, subgroups 7 and 8 tests shall be sufficient to verify the truth table.
  - 4.4.2 Group C inspection. The group C inspection end-point electrical parameters shall be as specified in table II herein.

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TABLE II. <u>Electrical test requirements</u>.

Test requirements	Subgroups (in accordance with MIL-STD-883, method 5005, table I)	Subgroups (in accordance with MIL-PRF-38535, table III)	
	Device class M	Device class Q	Device class V
Interim electrical parameters (see 4.2)			1
Final electrical parameters (see 4.2)	<u>1</u> / 1, 2, 3, 7, 8, 9, 10, 11	<u>1</u> / 1, 2, 3, 7, 8, 9, 10, 11	<u>2</u> / 1, 2, 3, 7, 8, 9, 10, 11
Group A test requirements (see 4.4)	1, 2, 3, 4, 7, 8, 9, 10, 11	1, 2, 3, 4, 7, 8, 9, 10, 11	1, 2, 3, 4, 7, 8, 9, 10, 11
Group C end-point electrical parameters (see 4.4)	1, 2, 3	1, 2, 3	1, 2, 3
Group D end-point electrical parameters (see 4.4)	1, 2, 3	1, 2, 3	1, 2, 3
Group E end-point electrical parameters (see 4.4)	1, 7, 9	1, 7, 9	1, 7, 9

<sup>1/</sup> PDA applies to subgroup 1.

- 4.4.2.1 Additional criteria for device class M. Steady-state life test conditions, method 1005 of MIL-STD-883:
  - a. Test condition A, B, C or D. The test circuit shall be maintained by the manufacturer under document revision level control and shall be made available to the preparing or acquiring activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in test method 1005 of MIL-STD-883.
  - b.  $T_A = +125^{\circ}C$ , minimum.
  - c. Test duration: 1,000 hours, except as permitted by method 1005 of MIL-STD-883.
- 4.4.2.2 Additional criteria for device classes Q and V. The steady-state life test duration, test condition and test temperature, or approved alternatives shall be as specified in the device manufacturer's QM plan in accordance with MIL-PRF-38535. The test circuit shall be maintained under document revision level control by the device manufacturer's TRB in accordance with MIL-PRF-38535 and shall be made available to the acquiring or preparing activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in test method 1005 of MIL-STD-883.
  - 4.4.3 Group D inspection. The group D inspection end-point electrical parameters shall be as specified in table II herein.
- 4.4.4 <u>Group E inspection</u>. Group E inspection is required only for parts intended to be marked as radiation hardness assured (see 3.5 herein).
  - a. End-point electrical parameters shall be as specified in table II herein.
  - b. For device classes Q and V, the devices or test vehicle shall be subjected to radiation hardness assured tests as specified in MIL-PRF-38535 for the RHA level being tested. For device class M, the devices shall be subjected to radiation hardness assured tests as specified in MIL-PRF-38535, appendix A for the RHA level being tested. All device classes must meet the postirradiation end-point electrical parameter limits as defined in table I at T<sub>A</sub> = +25°C ±5°C, after exposure, to the subgroups specified in table II herein.
  - c. When specified in the purchase order or contract, a copy of the RHA delta limits shall be supplied.

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<sup>2/</sup> PDA applies to subgroups 1 and 7.

#### 5. PACKAGING

5.1 <u>Packaging requirements</u>. The requirements for packaging shall be in accordance with MIL-PRF-38535 for device classes Q and V or MIL-PRF-38535, appendix A for device class M.

#### 6. NOTES

- 6.1 <u>Intended use</u>. Microcircuits conforming to this drawing are intended for use for Government microcircuit applications (original equipment), design applications, and logistics purposes.
- 6.1.1 <u>Replaceability</u>. Microcircuits covered by this drawing will replace the same generic device covered by a contractor-prepared specification or drawing.
  - 6.1.2 Substitutability. Device class Q devices will replace device class M devices.
- 6.2 <u>Configuration control of SMD's</u>. All proposed changes to existing SMD's will be coordinated with the users of record for the individual documents. This coordination will be accomplished in accordance with MIL-STD-973 using DD Form 1692, Engineering Change Proposal.
- 6.3 <u>Record of users</u>. Military and industrial users should inform Defense Supply Center Columbus when a system application requires configuration control and which SMD's are applicable to that system. DSCC will maintain a record of users and this list will be used for coordination and distribution of changes to the drawings. Users of drawings covering microelectronic devices (FSC 5962) should contact DSCC-VA, telephone (614) 692-0525.
- 6.4 <u>Comments</u>. Comments on this drawing should be directed to DSCC-VA, Columbus, Ohio 43216-5000, or telephone (614) 692-0674.
- 6.5 <u>Abbreviations, symbols, and definitions</u>. The abbreviations, symbols, and definitions used herein are defined in MIL-PRF-38535 and MIL-HDBK-1331.
  - 6.6 Sources of supply.
- 6.6.1 <u>Sources of supply for device classes Q and V</u>. Sources of supply for device classes Q and V are listed in QML-38535. The vendors listed in QML-38535 have submitted a certificate of compliance (see 3.6 herein) to DSCC-VA and have agreed to this drawing.
- 6.6.2 <u>Approved sources of supply for device class M.</u> Approved sources of supply for class M are listed in MIL-HDBK-103. The vendors listed in MIL-HDBK-103 have agreed to this drawing and a certificate of compliance (see 3.6 herein) has been submitted to and accepted by DSCC-VA.

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## STANDARD MICROCIRCUIT DRAWING BULLETIN

DATE: 96-10-15

Approved sources of supply for SMD 5962-96893 are listed below for immediate acquisition information only and shall be added to MIL-HDBK-103 and QML-38535 during the next revision. MIL-HDBK-103 and QML-38535 will be revised to include the addition or deletion of sources. The vendors listed below have agreed to this drawing and a certificate of compliance has been submitted to and accepted by DSCC-VA. This bulletin is superseded by the next dated revision of MIL-HDBK-103 and QML-38535.

Standard microcircuit drawing PIN <u>1</u> /	Vendor CAGE number	Vendor similar PIN <u>2</u> /
5962-9689301QXA	01295	SNJ55976A1WD
5962-9689302QXA	01295	SNJ55976A2WD

- 1/ The lead finish shown for each PIN representing a hermetic package is the most readily available from the manufacturer listed for that part. The device manufacturers listed herein are authorized to supply alternate lead finishes "A", "B", or "C" at their discretion. Contact the listed approved source of supply for further information.
- 2/ Caution. Do not use this number for item acquisition. Items acquired to this number may not satisfy the performance requirements of this drawing.

Vendor CAGE <u>number</u>

01295

Vendor name and address

Texas Instruments Incorporated 13500 N. Central Expressway P.O. Box 655303 Dallas, TX 75265 Point of contact:

I-20 at FM 1788 Midland, TX 79711-0448

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